



## Advances in 3D Sensing Techniques and Its Applications

Guest Editor:

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Deadline for manuscript  
submissions:

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### Message from the Guest Editor

Dear Colleagues,

Three-dimensional (3D) sensing plays an important role in advanced manufacturing, reverse engineering, virtual reality, etc. We would like to invite you to submit original research papers for the related topics, which are detailed below. In addition, research papers which discuss novel optical 3D sensing methods, measurement systems and applications of computer vision are also welcome. This Special Issue focuses on the 3D measurement of shapes and deformations using optical methods and its applications.

In this Special Issue, original research articles and reviews are welcome. The research areas may include, but are not limited to:

- Three-dimensional shape and deformation measurement;
- High-speed and dynamic 3D measurement;
- Computer vision;
- Fringe projection profilometry;
- Digital image correlation (DIC);
- Interferometry;
- Optical method;
- Fringe analysis;
- Phase retrieval;
- Image processing.

I look forward to receiving your contributions.





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## Editor-in-Chief

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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